

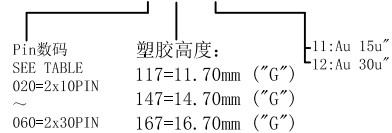
**RoHS Compliant HF**

REV.	ECN.NO.	MODIFY.CONTENT
X1	2023-03-14	NEW

**NOTES:**

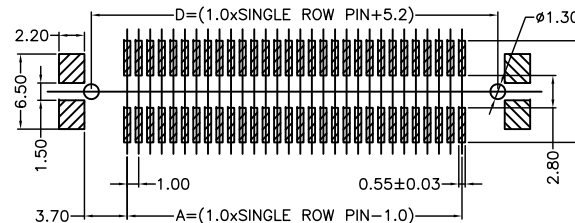
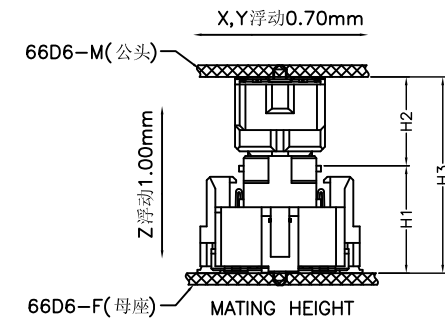
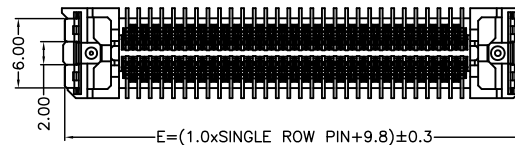
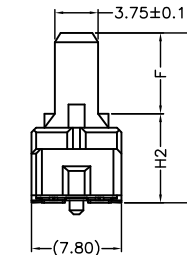
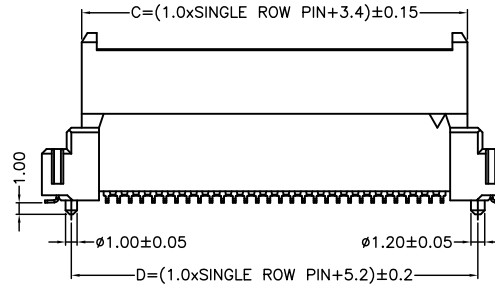
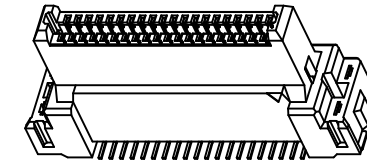
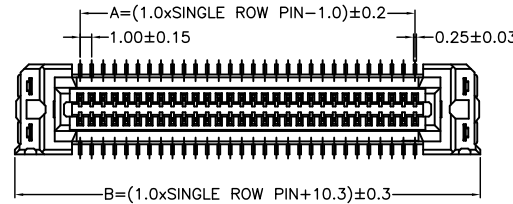
- FINISH:
  - HOUSING: POLYAMIDE BLACK,UL94V-0.
  - CONTACT: PHOSPHOR BRONZE,GOLD (SEE P/N) PLATED IN CONTACT AREA, GOLD FLASH PLATED IN SOLDER AREA, 50u" MIN. NICKEL UNDERPLATED OVERALL.
  - GROUND: BRASS,80u" MIN MATTE TIN PLATED OVER 50u" MIN NICKEL UNDERPLATED OVERALL.
- ELECTRICAL:
  - CURRENT RATING: 0.5A/PIN
  - VOLTAGE RATING: 125V AC/DC.
  - CONTACT RESISTANCE: 65mΩ MAX.
  - INSULATION RESISTANCE: 250V DC/0.1S/1000MΩ
- Max Processing Temp:265°C Seconds 40S
- FLOATING RANGE OF THIS CONNECTOR IS 0.7MM MAX.  
THE MAXIMUM CYCLE TIME OF THE FLOATING OPERATION IS IN ACCORDANCE WITH THE MATING CYCLE OF THE CONNECTOR
- PLEASE USE THE CONNECTORS WITHIN THE SPECIFIED PCB DISTANCE.  
PLEASE REFER TO THE DRAWINGS OF MATING CONNECTOR
- BLEMISH AND HIT MARK CAN BE OCCURED THROUGH OUT THE MANUFACTURING PROCESS
- ORDER INFORMATION:

FB01-100MXXXXXX4XX



**TABLE:**

No. OF PIN	A	B	C	D	E
020=2x10PIN	9.00	20.30	13.40	15.20	19.80
030=2x15PIN	14.00	25.30	18.40	20.20	24.80
040=2x20PIN	19.00	30.30	23.40	25.20	29.80
050=2x25PIN	24.00	35.30	28.40	30.20	34.80
060=2x30PIN	29.00	40.30	33.40	35.20	39.80



RECOMMENDED PCB LAYOUT  
PCB BOARD TOLFRANCF±0.05

"G" STACK HEIGHT	H2	F
11.70mm	4.70	7.00
14.70mm	7.70	
16.70mm	9.70	

H1	H2	"H3" MATING HEIGHT
9.30	4.70	15.00
	7.70	18.00
14.30	9.70	20.00
	4.70	20.00
	7.70	23.00
	9.70	25.00

GENERAL TOLERANCE	DWG.NO.	F B01-100MXXXXXX400	PART.NO.	F B01-100MXXXXXX4XX	DRAWN	Brian 2023-03-14
x.±0.50	REV.	X1	TITLE	浮动板对板1.0Pitch公座	CHECKED	
.x±0.25	SIZE		SHEET	1 OF 1	APPROVED	
.xx±0.15	A4					

UNIT: mm SCALE: 1:1

**OLN** 东莞市欧联电子科技有限公司  
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